

General Description

The HSU4600 is the high performance complementary N-ch and P-ch MOSFETs with high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The HSU4600 meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

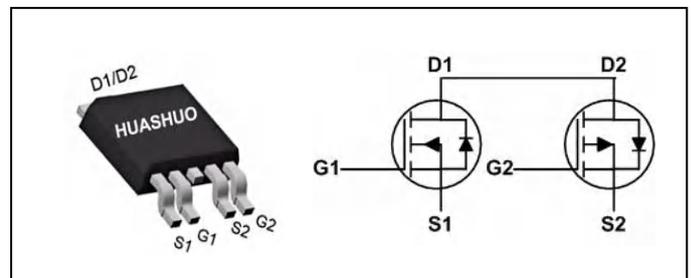
Features

- 100% EAS Guaranteed
- Green Device Available
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Advanced high cell density Trench Technology

Product Summary

BVDSS	RDSON	ID
20V	5.6mΩ	45A
-20V	9.5mΩ	-25A

TO252-4L Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating		Units
		N-Ch	P-Ch	
V_{DS}	Drain-Source Voltage	20	-20	V
V_{GS}	Gate-Source Voltage	± 12	± 12	V
$I_D@T_C=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	45	-25	A
$I_D@T_C=70^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	36	-20	A
I_{DM}	Pulsed Drain Current ²	180	-100	A
EAS	Single Pulse Avalanche Energy ³	100	56	mJ
I_{AS}	Avalanche Current	20	-15	A
$P_D@T_C=25^\circ C$	Total Power Dissipation ⁴	35	35	W
T_{STG}	Storage Temperature Range	-55 to 150	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	-55 to 150	$^\circ C$

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	---	62	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	---	3.6	$^\circ C/W$



N-Channel Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	20	---	---	V
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =7.5V , I _D =10A	---	5.6	8	mΩ
		V _{GS} =4.5V , I _D =10A	---	6.2	9	
		V _{GS} =2.5V , I _D =6A	---	8	12	
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	0.4	0.7	1.0	V
I _{DSS}	Drain-Source Leakage Current	V _{DS} =20V , V _{GS} =0V , T _J =25°C	---	---	1	uA
		V _{DS} =20V , V _{GS} =0V , T _J =55°C	---	---	5	
I _{GSS}	Gate-Source Leakage Current	V _{GS} = ± 12V , V _{DS} =0V	---	---	± 100	nA
R _g	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz	---	1.7	---	Ω
Q _g	Total Gate Charge (4.5V)	V _{DS} =10V , V _{GS} =4.5V , I _D =10A	---	20	---	nC
Q _{gs}	Gate-Source Charge		---	4.4	---	
Q _{gd}	Gate-Drain Charge		---	3.2	---	
T _{d(on)}	Turn-On Delay Time	V _{DD} =10V , V _{GS} =4.5V , R _G =3.3Ω, I _D =10A	---	21	---	ns
T _r	Rise Time		---	13	---	
T _{d(off)}	Turn-Off Delay Time		---	25	---	
T _f	Fall Time		---	19	---	
C _{iss}	Input Capacitance	V _{DS} =10V , V _{GS} =0V , f=1MHz	---	1572	---	pF
C _{oss}	Output Capacitance		---	221	---	
C _{rss}	Reverse Transfer Capacitance		---	205	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I _S	Continuous Source Current ^{1,5}	V _G =V _D =0V , Force Current	---	---	45	A
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =1A , T _J =25°C	---	---	1.2	V

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The EAS data shows Max. rating . The test condition is V_{DD}=10V,V_{GS}=4.5V,L=0.5mH,I_{AS}=20A
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.



P-Channel Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250uA	-20	---	---	V
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =-7.5V, I _D =-10A	---	9.5	12	mΩ
		V _{GS} =-4.5V, I _D =-10A	---	10.5	14	
		V _{GS} =-2.5V, I _D =-6A	---	15	20	
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =-250uA	-0.4	-0.7	-1.0	V
I _{DSS}	Drain-Source Leakage Current	V _{DS} =-20V, V _{GS} =0V, T _J =25°C	---	---	1	uA
		V _{DS} =-20V, V _{GS} =0V, T _J =55°C	---	---	5	
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±12V, V _{DS} =0V	---	---	±100	nA
R _g	Gate Resistance	V _{DS} =0V, V _{GS} =0V, f=1MHz	---	10	---	Ω
Q _g	Total Gate Charge (-4.5V)	V _{DS} =-10V, V _{GS} =-4.5V, I _D =-10A	---	26	---	nC
Q _{gs}	Gate-Source Charge		---	4.2	---	
Q _{gd}	Gate-Drain Charge		---	19	---	
T _{d(on)}	Turn-On Delay Time	V _{DD} =-10V, V _{GS} =-10V, R _G =3.3Ω, I _D =-10A	---	16.4	---	ns
T _r	Rise Time		---	26	---	
T _{d(off)}	Turn-Off Delay Time		---	35	---	
T _f	Fall Time		---	17	---	
C _{iss}	Input Capacitance	V _{DS} =-10V, V _{GS} =0V, f=1MHz	---	1905	---	pF
C _{oss}	Output Capacitance		---	198	---	
C _{rss}	Reverse Transfer Capacitance		---	165	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I _S	Continuous Source Current ^{1,5}	V _G =V _D =0V, Force Current	---	---	-25	A
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V, I _S =-1A, T _J =25°C	---	---	-1.2	V

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The EAS data shows Max. rating . The test condition is V_{DD}=-10V,V_{GS}=-4.5V,L=0.5mH,I_{AS}=-15A
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

N-Channel Typical Characteristics

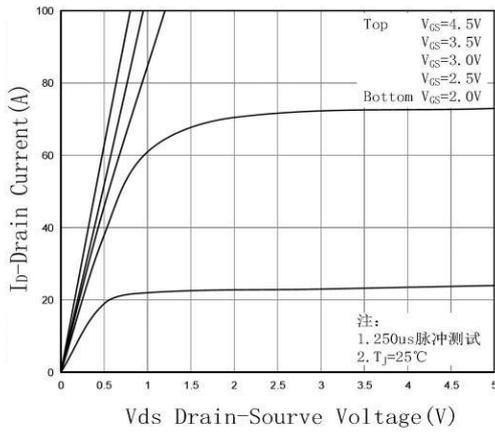


Fig.1 Output Characteristic

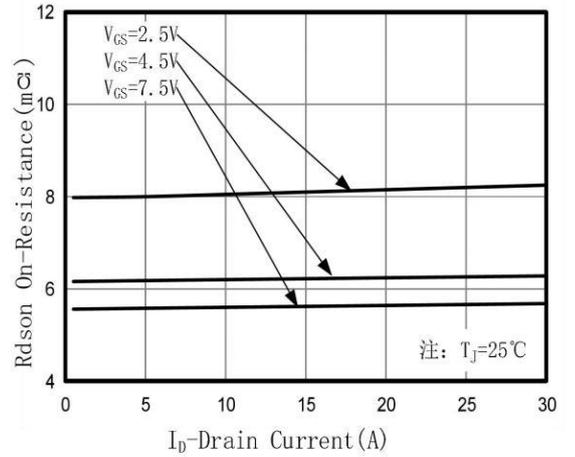


Fig.2 On-Resistance vs. Drain Current

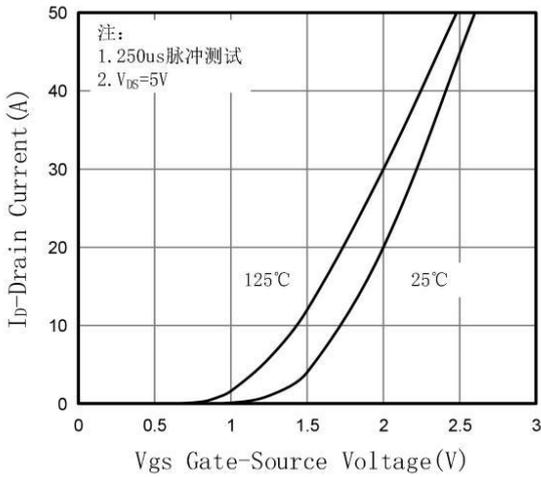


Fig.3 Transfer Characteristic

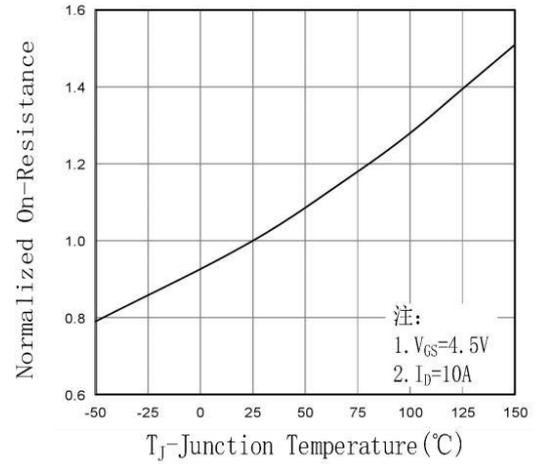


Fig.4 On-Resistance vs. Junction Temperature

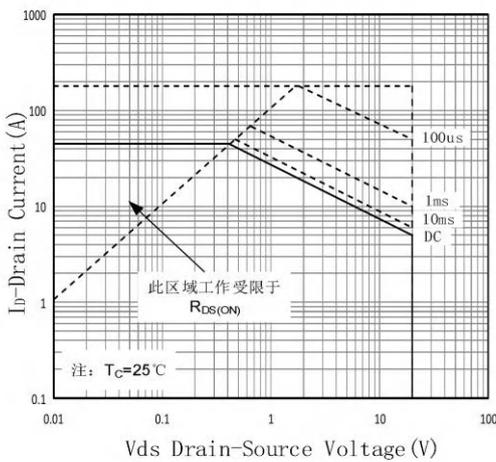


Fig.5 Safe Operation Area

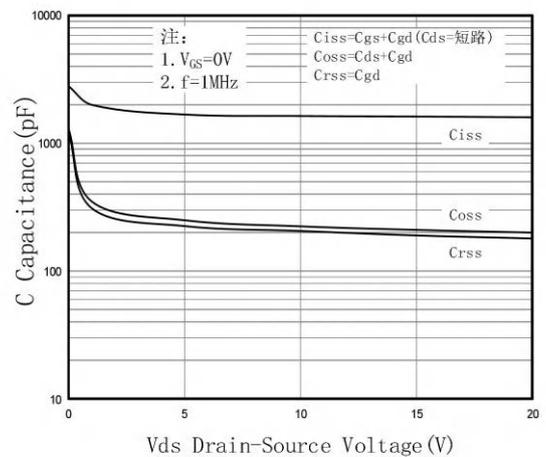


Fig.6 Capacitance Characteristic

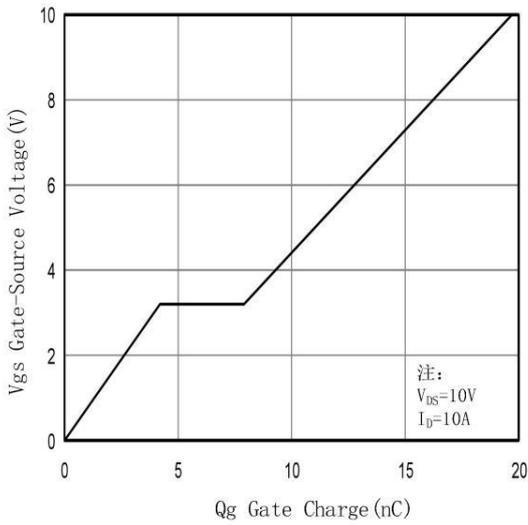


Fig.7 Gate-Charge Characteristic

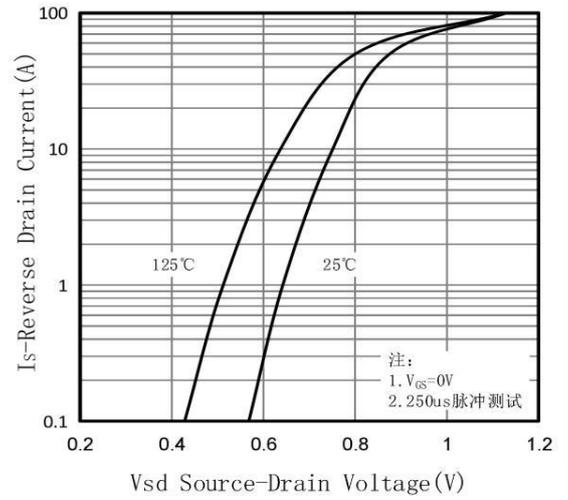


Fig.8 Body Diode Characteristic

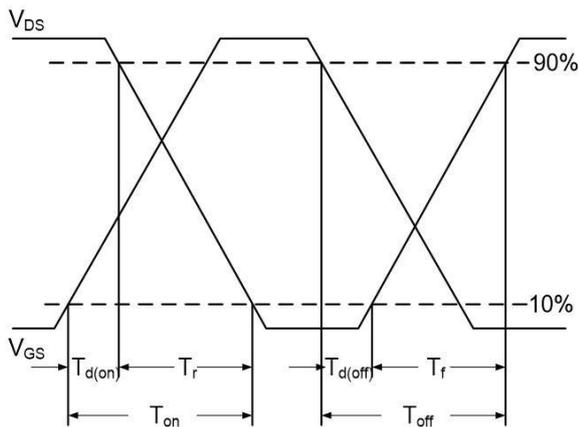


Fig.9 Switching Time Waveform

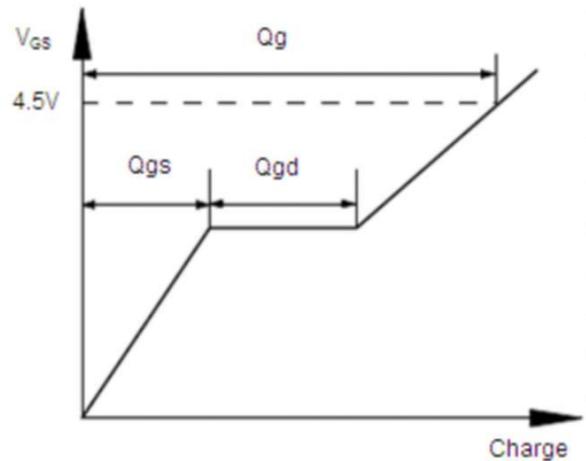


Fig.10 Gate Charge Waveform

P-Channel Typical Characteristics

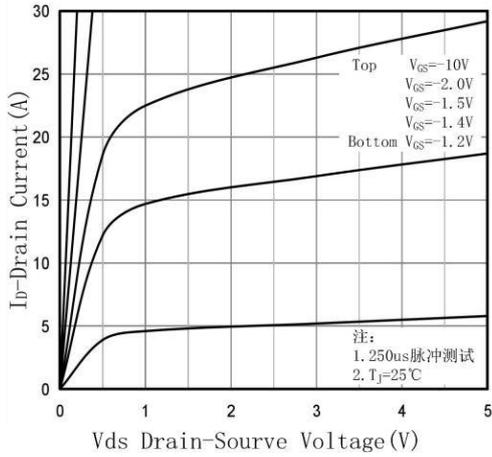


Fig.1 Output Characteristic

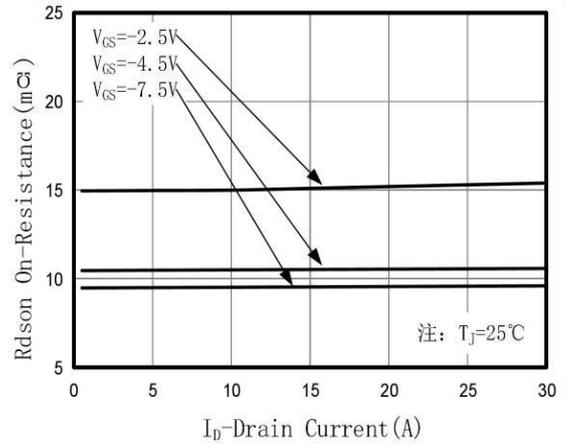


Fig.2 On-Resistance vs. Drain Current

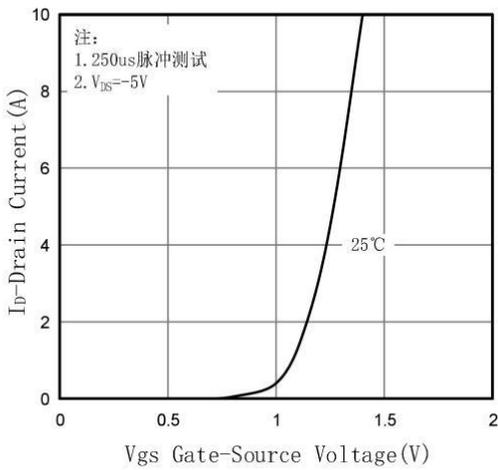


Fig.3 Transfer Characteristic

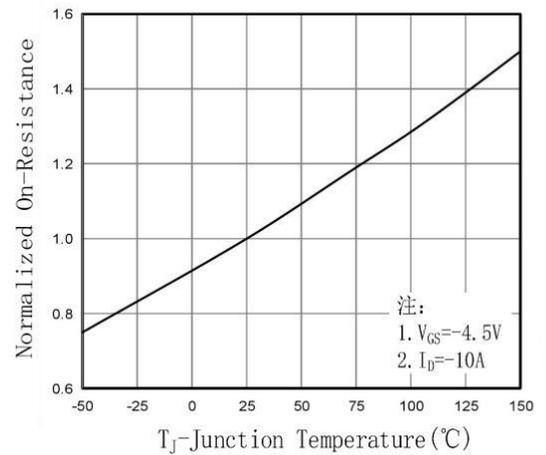


Fig.4 On-Resistance vs. Junction Temperature

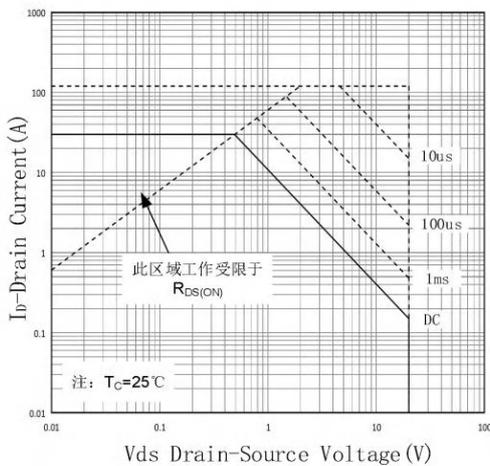


Fig.5 Safe Operation Area

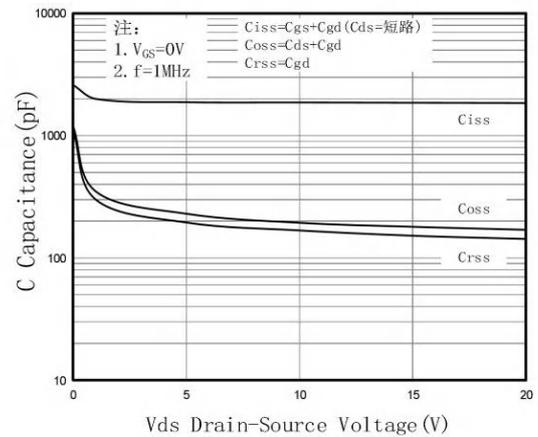


Fig.6 Capacitance Characteristic

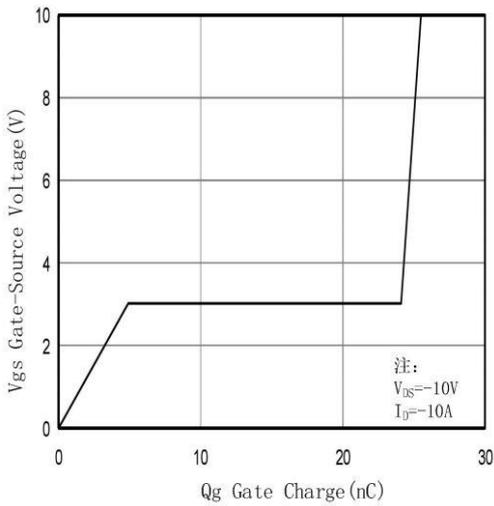


Fig.7 Gate-Charge Characteristic

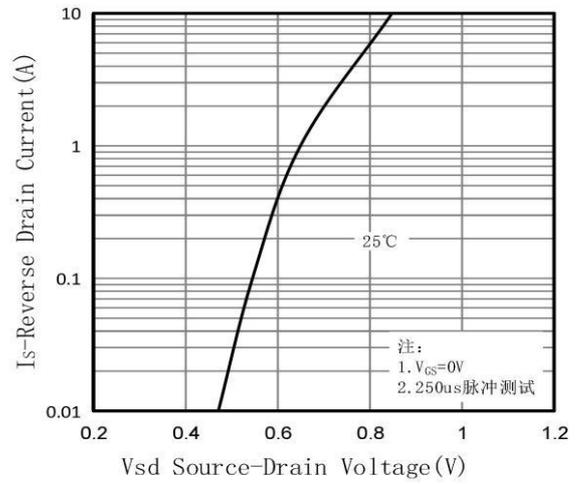


Fig.8 Body Diode Characteristic

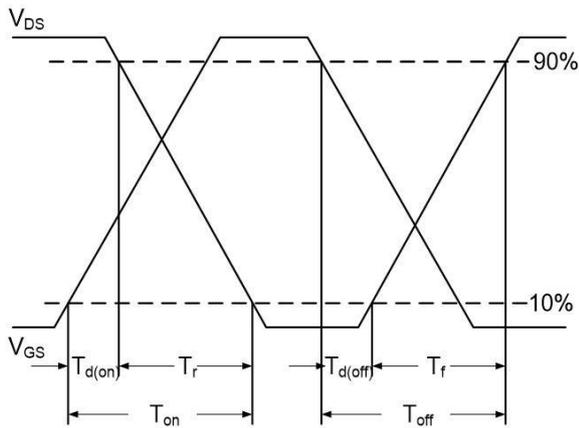


Fig.9 Switching Time Waveform

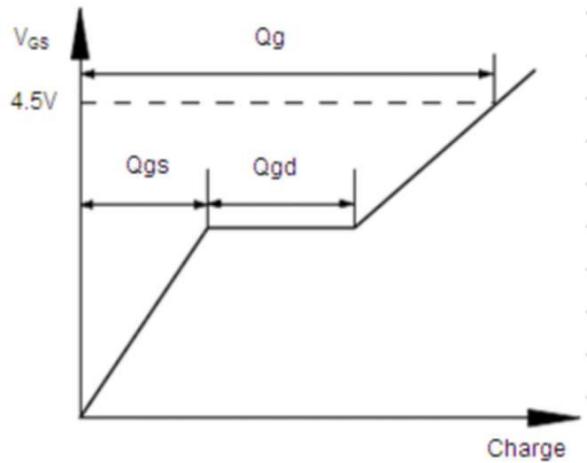
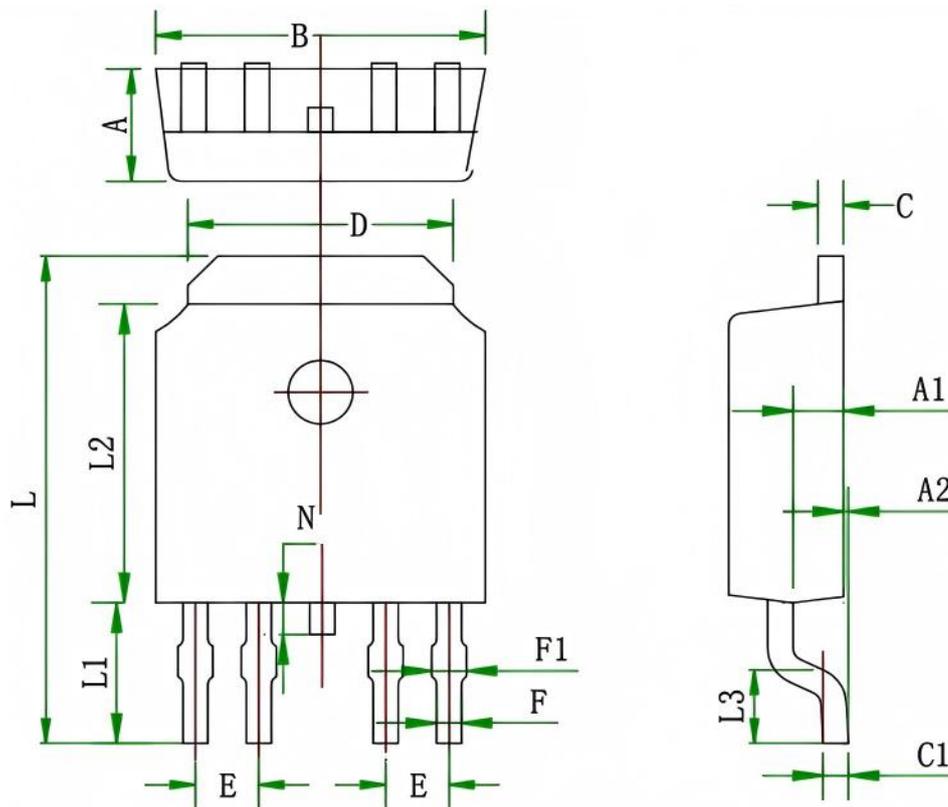


Fig.10 Gate Charge Waveform

Ordering Information

Part Number	Package code	Packaging
HSU4600	TO252-4L	2500/Tape&Reel

TO252-4L Package Outline


Symbol	Min(mm)	Typ(mm)	Max(mm)
A	2.22	2.30	2.38
A1	0.93	1.01	1.08
A2	0.02	0.10	0.15
B	6.52	6.60	6.68
C	0.48	0.50	0.54
C1	0.48	0.50	0.54
D	5.22	5.32	5.42
E	1.22	1.27	1.32
F	0.40	0.50	0.60
F1	0.50	0.60	0.70
L	9.77	9.97	10.17
L1	2.77	2.87	2.97
L2	6.02	6.10	6.18
L3	1.40	1.50	1.60
N	0.55	0.65	0.75



HSU4600 Marking:

